

## EPS Exceptional Technical Achievement Award

### Past Recipients

2022 Yueping Zhang, Diuxian Liu and Xiaoxiong Gu

for seminal contributions to the development of antenna-in-package (AiP) technology that have had a profound impact on electronic packaging.

2021 Beth Keser and Tanja Braun

for seminal contributions and leadership in Fan-out Wafer Level Packaging.

2020 Bing Dang

for contributions to the research and development of 2.5D and 3D system integration, interconnect technologies and materials processes.

2019 Chuan-Seng Tan

for technical contributions and leadership in 3D packaging and integration, particularly on solderless Cu-Cu bonding and innovations in TSV technology.

2018 Muhannad Bakir, Kuan-Neng Chen and Katsuyuki Sakuma

for contributions to 2.5D and 3D IC heterogeneous integration, with focus on interconnect technologies.

2017 Ephraim Suhir

for the development of numerous probabilistic design concepts that enable effective and rapid assessment of the probability of failure of electronic products.

2016 Xiaobing Luo

for exceptional contribution in modeling and experimental characterization of IC/LED packaging, focusing primarily on thermal packaging and innovations in packaging processes.

2015 Xiaowu Zhang

for major contributions in the area of 2.5D/3D ICs integration, focusing primarily on process development and reliability, and stress sensor technology.

2014 Pradeep Lall

for exceptional contributions in the areas of shock, drop and vibration reliability of electronic products.

2013 Yong Liu

for extensive contributions to analog and power packaging, focusing primarily on manufacturing assembly process modeling, reliability prediction, and innovations in analog and power packaging

2012 Andrew A. O. Tay

for exceptional contributions to reliability modeling and the understanding of delamination and popcorn failure of IC packages.

2011 Xuejun Fan

for major contributions in the area of modeling and characterization of moisture-related reliability in IC packaging, including theoretical model development, validation, numerical implementation, test methodology development and design.

2010 Michael Pecht

for his seminal contributions in the area of electronics reliability from which he developed the new and significant field of prognostics for electronics.

2009 Sheng Liu

for his pioneering work on multi-physics and multi-scale modeling for manufacturing process modeling and reliability qualification coupled with the development of various validation tools.

2008 James Jian-Qiang Lu

for his pioneering contributions to and leadership in 3D integration/packaging, spanning nearly 20 years and resulting in more than 150 publications in refereed journals, book chapters, trade press journals and conferences.

2007 Chin C. Lee

for his pioneering contributions to fluxless soldering and bonding technology.

2006 Ning-Cheng Lee

for contributions to surface mount technology and electronic packaging assembly.

2005 Tseung-Yuen Tseng

for his contributions to the applied technology and basic science in electronic ceramics, in particular to ceramic capacitors.

2004 Johan Liu

for his major research contributions in the area of conductive adhesives for electronic interconnect applications for a wide variety of industrial and consumer products.

2003 Michael McShane, Paul Lin and Howard Wilson

for co-inventing the PBGA package that resulted in new and revolutionary applications for existing electronics packaging technologies.

2002 C.P. Wong